

IPEC 472 Automated CMP Tool



The IPEC 472 wafer polisher is a fully automated, precision tool for CMP polishing of semiconductor wafers used to achieve flatness, uniformity, and planarization on patterned/device wafers. The 472 features automatic wafer handling and is capable of two platen, two-step polishing processing to maximize wafer throughput capability and quality. Designed to planarize wafers from 100mm to 200mm, the 472 is ideally suited for materials polishing applications that require repeatability with operational and processing flexibility.

STD FEATURES

- Fully automated precision polishing
- Two platen process for post polish buff
- Multiple slurry dispense
- In-situ pad conditioner
- Material compatibility for medium and low pH slurries (1-12)
- Down force up to 750lbs
- Controllable wafer back pressure
- Polish head clean station
- External interface for end point capability
- Temperature controlled platens

AVAIL OPTIONS

- SECS II Interface

DIMENSIONS		FACILITIES	
mm	1702W x 2464D x 2337H	Power	208 VAC, 3-PH, 50/60Hz
Inches	67W x 97D x 92H	DI Water	6gpm, avg Pressure: 25 – 30psi, min
		CDA	Peak 10 SCFM
		Compressed Air	6 SCFM